

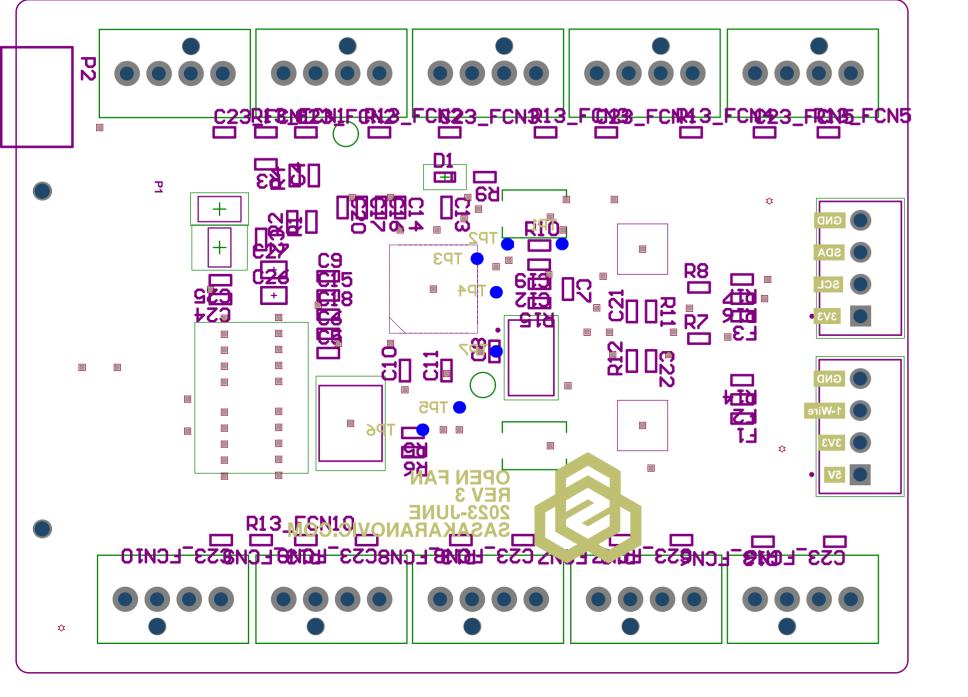
Top Overlay

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	O. 010mm	3.5	
1	Top Layer		O.035mm		
	Dielectric 1	FR-4	1.500mm	4.29	
2	Bottom Layer		0.035mm		
	Bottom Solder	Solder Resist	O. 010mm	3.5	
	Bottom Overlay				

Total board thickness:

1.590mm

Symbol	Count	Hole Size	Plated	Hole Type	Via/Pad
	2	1.200mm	PTH	Round	Pad
\$	3	3.200mm	PTH	Round	Pad
$\nabla$	10	1.300mm	PTH	Round	Pad
0	48	1.100mm	PTH	Round	Pad
	67	0.400mm	PTH	Round	Via
	130 Total				



**Bottom Overlay** 

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	O. 010mm	3.5	
1	Top Layer		0.035mm		
	Dielectric 1	FR-4	1.500mm	4.29	
2	Bottom Layer		O.035mm		
	Bottom Solder	Solder Resist	O. 010mm	3.5	
	Bottom Overlay				
Total board thickness:			1.590mm		

Symbol	Count	Hole Size	Plated	Hole Type	Via/Pad
	2	1.200mm	PTH	Round	Pad
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	130 Total				